

Thermal Conductive Board

Product Description

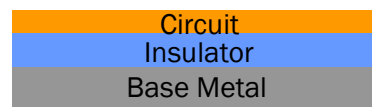
Thermal Conductive Board (TCB), or Insulated Metal Substrate (IMS), provides the advantages of high thermal conductivity, reliability, and thermal resistance. TCB is a sandwich structure, which includes layers of copper foil, insulator, and base metal. The insulator is made by a unique polymer composite that combine epoxy resin and high thermal conductivity filler, and the thermal conductivity is much higher than the traditional epoxy filled glass fiber system.

Features

- Lower Tg
- Excellent thermal conductivity
- Customized substrate structure available
- Excellent solder resistance
- RoHS Complaint
- Excellent reliability
- Over 15 Patents

Specifications

Characteristics	TCB-EPS
Panel Size [mm]	510 x 610, or etc.
Base Metal [mm]	1.0, 1.5, 2.0, or etc.
Dielectric Layer thickness [μm]	100, 150, or etc.
Circuit [oz]	1, 2, 3, or etc.



General Properties

Characteristics	TCB-EPS	Test Method
Thermal resistance [$^{\circ}\text{C}/\text{W}$, 100μm]	<0.12	ASTM D5470
Flammability	V-0	UL 94, internal test
Break down voltage [AC KV/mm]	>25	JIS C 2110
Peeling strength [Kg/cm]	> 1.4	JIS C 6481
Solder heat resistance, 260 $^{\circ}\text{C}$ [mins]	>60	
Glass transition temperature [$^{\circ}\text{C}$]	55	IPC-TM-650 2.4.25